

General Description

The WSD30L40DN is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD30L40DN meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

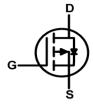
BVDSS	RDSON	ID
-30V	11mΩ	-40A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN3X3-8 Pin Configuration





Absolute Maximum Ratings

		Rating		
Symbol	Parameter	10s	Steady State	Units
V _{DS}	Drain-Source Voltage	-	30	V
V _{GS}	Gate-Source Voltage	4	20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-	40	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ -10V ¹	-	25	А
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-14.5	-12	А
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ -10V ¹	-10.5	-9.8	А
I _{DM}	Pulsed Drain Current ²	-70		А
EAS	Single Pulse Avalanche Energy ³ 81		31	mJ
I _{AS}	Avalanche Current	-	-18	
P _D @T _C =25℃	Total Power Dissipation ⁴	3	32.9	
P _D @T _A =25℃	Total Power Dissipation ⁴	3.6	3.1	W
T _{STG}	Storage Temperature Range	-55	-55 to 150	
TJ	Operating Junction Temperature Range	-55	-55 to 150	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		75	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		40	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		3.8	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I _D =-1mA		-0.0232		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-20A		11	14	
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-10A		18	24	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} . In =-250uA	-1.3	-1.8	-2.3	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =-2500A		4.6		mV/℃
	Drain Source Leakage Current	V_{DS} =-24V , V_{GS} =0V , T_J =25 $^{\circ}$ C			-1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =55℃			-5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-30A		15		S
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		9		Ω
Q_g	Total Gate Charge (-4.5V)	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-20A		30		
Q _{gs}	Gate-Source Charge			1.2		nC
Q _{gd}	Gate-Drain Charge			11		
T _{d(on)}	Turn-On Delay Time			11		
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =6 Ω		11		-
T _{d(off)}	Turn-Off Delay Time	I _D =-1A ,R _L =15Ω		101		ns
T _f	Fall Time			60		1
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		1380		
C _{oss}	Output Capacitance			280		pF
C _{rss}	Reverse Transfer Capacitance			217		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.5mH , I _{AS} =-18A	78			mJ

Diode Characteristics

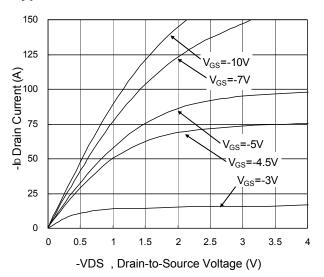
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			-20	Α
I _{SM}	Pulsed Source Current ^{2,6}				-70	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1	V
t _{rr}	Reverse Recovery Time	IF=-20A,dI/dt=100A/µs, T _J =25°C		20		nS
Qrr	Reverse Recovery Charge			8		nC

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper, $t \le 10$ sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.5mH, I_{AS} =-18A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.



Typical Characteristics



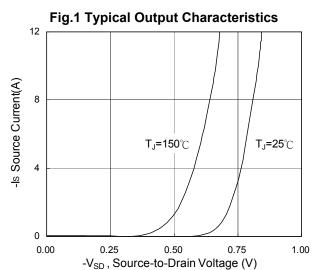


Fig.3 Forward Characteristics of Reverse

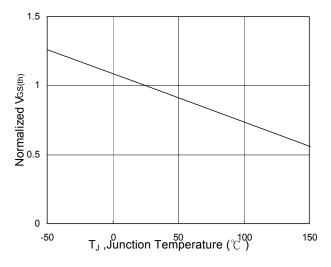


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

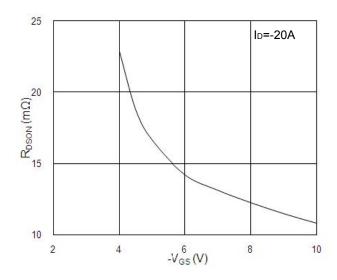


Fig.2 On-Resistance vs. G-S Voltage

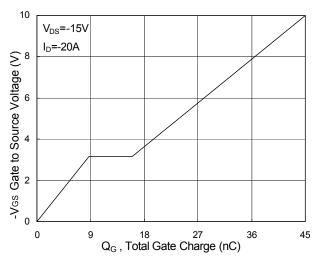


Fig.4 Gate-Charge Characteristics

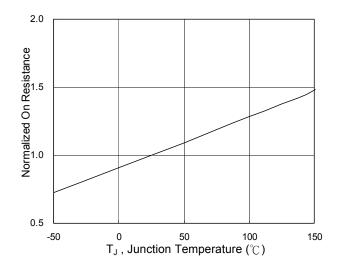
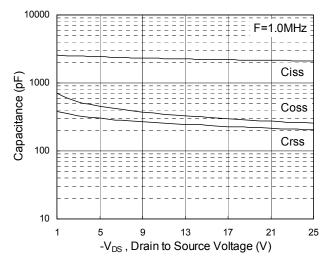


Fig.6 Normalized R_{DSON} vs. T_J







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Fig.7 Capacitance

Fig.8 Safe Operating Area

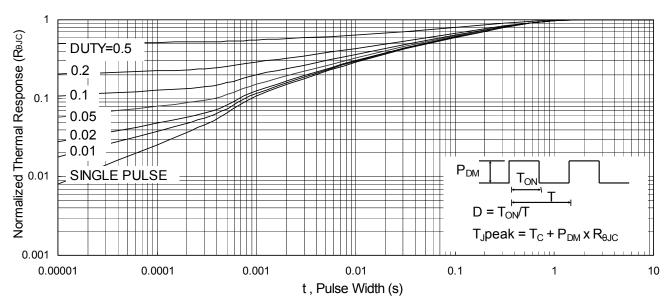
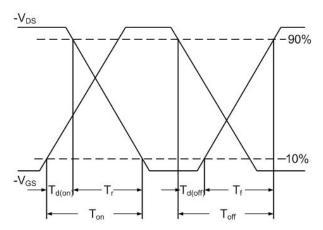


Fig.9 Normalized Maximum Transient Thermal Impedance





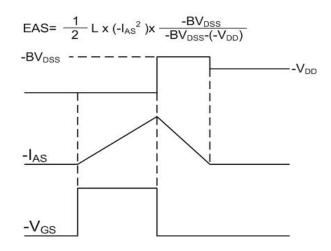


Fig.11 Unclamped Inductive Switching Waveform



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